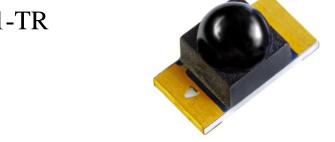


Data sheet

Part number: TPS1195WB-1-TR





| Package | Dome lens package, Photo transistor (Photo detector) Visible light cut resin Outer dimension $3.2 \times 1.6 \times 1.85 \text{mm}$ (L x W x H) |
|------------------|---|
| Product features | Peak sensitivity wavelength 900nm Lead–free soldering compatible RoHS2 compliant |

Recommended applications

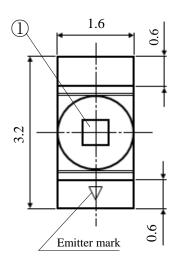
- •Industrial equipment : Light curtains, sensor for security equipment, photoelectric sensor
- •Consumer equipment : Remote controller, disk detectors (CD/DVD/Blu-ray) etc.

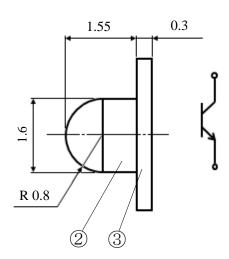


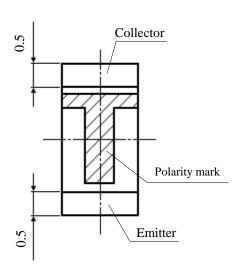
Outline dimensions

TPS1195WB-1-TR

Unit :mm
Weight :7.81mg
Tolerance : \pm 0.1

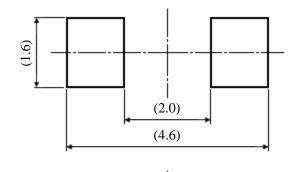


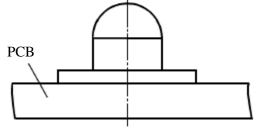




| NO. | PART NAME MATERIALS | | QTY. |
|-----|---------------------|---------------|------|
| 1) | Photo transistor | Si | 1 |
| 2 | Mold resin | Epoxy resin | 1 |
| 3 | Substrate | Glass fabrics | 1 |

Recommended Soldering Pad





Unit : mm



Specifications

TPS1195WB-1-TR

[Absolute Maximum Ratings]

(Ta=25°C)

| | | | (/ |
|---------------------------|------------------|-----------------|--------------|
| ITEM | SYMBOL | MAXIMUM RATINGS | UNIT |
| Power Dissipation | Pc | 75 | mW |
| Collector-Emitter Voltage | V _{CEO} | 30 | V |
| Emitter-Collector Voltage | V _{ECO} | 5 | V |
| Collector Current | Ic | 20 | mA |
| Operating Temperature | T _{opr} | -40 to +85 | $^{\circ}$ C |
| Storage Temperature | T_{stg} | -40 to +100 | $^{\circ}$ |

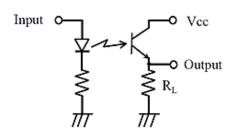
[Electro-Optical Characteristics]

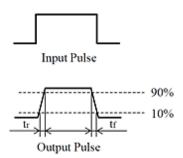
(Ta=25°C)

| | | | | | | | (14 20 0) |
|----------|--------------------------|----------------------|---|------|------|------|-----------|
| ITI | EM | SYMBOL | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| Dark | Current | I_{CEO} | $V_{CEO} = 10V$ | - | - | 0.1 | μΑ |
| Photo | ocurrent | Ic | $V_{CE} = 5V$, $1 \text{ Ee} = 5\text{mW/cm}^2$ | 5.5 | - | 11.0 | mA |
| Peak W | avelength | λp | - | - | 900 | - | nm |
| | or-Emitter on Voltage | V _{CE(Sat)} | Ic = 0.5 mA, 1 Ee = 10 mW/cm ² | - | 0.1 | - | V |
| Response | Rise Time | tr | $2 V_{CE} = 10V$ | - | 3.1 | - | μs |
| Time | Fall Time | tf | $Ic = 2mA$, $R_L = 100\Omega$ | - | 4.1 | - | με |

X1 Color temperature of light source : Use 2,856Kelvin tungsten filament lamp

※2 Response time test circuit





[Sorting for Photo current]

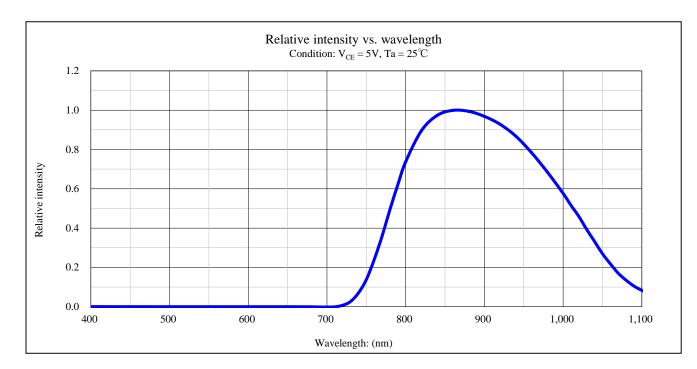
Photo Transistors shall be sorted out into the following ranks.

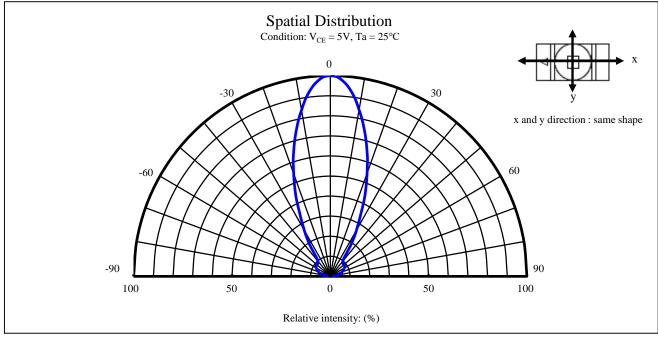
| Domlo | Photo Curre | Conditions | |
|-------|-------------|------------|------------------------|
| Rank | MIN. | MAX. | Conditions |
| 1 | 5.5 | 7.0 | V _{CE} =5V |
| 2 | 7.0 | 8.8 | Ee=5mW/cm ² |
| 3 | 8.8 | 11.0 | Ta=25°C |



Technical Data

TPS1195WB-1-TR







Soldering condition

TPS1195WB-1-TR

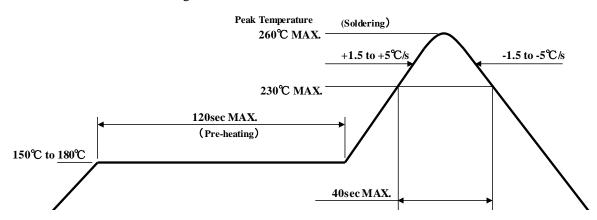
【Soldering Precaution】 (acc.to EIAJ-4701/300)

- 1. Heat stress during soldering will influence the reliability of LEDs, however that effect will vary on heating method. Also, if components of varying shape are soldered together, it is recommended to set the soldering pad temperature according to the component most vulnerable to heat (e.g., surface mount LED).
- 2. LED parts including the resin are not stable immediately after soldering (when they are not at room temperature), any mechanical stress may cause damage to the product. Please avoid such stress after soldering, especially stacking of the boards which may cause the boards to warp and any other types of friction with hard materials.
- 3. Recommended temperature profile for the Reflow soldering is listed as the temperature of the resin surface. Temperature distribution varies on heating method, PCB material, other components in the assembly, and mounting density.

Typically, when FR-4 PCB is mounted with one LED and heated via far infrared and hot air, the difference in temperature between PCB and LED resin will be around 5 to 10°C.

Please do not repeat the heating process in Reflow process more than twice.

[Recommended reflow soldering condition]



- Note 1 Temperature Profile for the reflow should be set to the surface temperature of resin which is on the top of LED. This should be the maximum temperature for soldering. Lowering the heating temperature and decreasing heating time is very effective in achieving higher reliability.
- Note 2 The reflow soldering process should be done up to twice (2 times Max). When second process is performed, interval between first and second process should be as short as possible to prevent absorption of moisture to resin of LED. The second soldering process should not be done until LEDs have returned to room temperature (by nature-cooling) after first soldering process.



Soldering condition

TPS1195WB-1-TR

- 4. If soldering manually, Stanley recommends using a soldering iron equipped with temperature control. During the actual soldering process, make sure that the soldering iron never touches the LED itself, and prevent the LED's electrode heating temperature from reaching above the heating temperature of the solder pad. All repairs must be performed only once in the same spot; please avoid reusing components.
- 5. During soldering process, immediately after iron tip is cleaned please make sure that the soldering iron reaches the appropriate temperature before using. Also, please avoid applying any types of pressure to the soldered components before the solder has cooled down and hardened, as it may deteriorate solder performance and solder quality.

[Recommended manual soldering condition]

| Temperature of iron tip | 350°C Max. |
|--------------------------|------------------|
| Soldering duration, time | 3sec.Max.,1 time |

6. When using adhesive material for temporary fixing, thermosetting resin or Ultraviolet radiation (UV) setting resin with heat is recommended.

《Curing conditions, Temperature:150°CMax./Time:120sec.Max.》

- 7. Flow soldering (dip soldering) is not recommended for this product.
- 8. Isopropyl alcohol is recommended for cleaning. Some chemicals, including Freon substitute detergents, might corrode the lens or the casing surface, which might cause discoloration, clouding, cracks and so on. Please review the reference chart below before cleaning. If water is used to clean (including the final cleaning process), please use pure water (not tap water), and completely dry the LED before using. Ultrasonic cleaning is not recommended.

| Cleaning agents | Recommended / Not recommended | |
|-------------------|-------------------------------|--|
| Isopropyl alcohol | ✓ Recommended | |
| Ethyl alcohol | ✓ Recommended | |
| Pure water | ✓ Recommended | |
| Trichloroethylene | x Not recommended | |
| Chlorothene | x Not recommended | |
| Acetone | x Not recommended | |
| Thinner | x Not recommended | |



Handling precautions

TPS1195WB-1-TR

[Other precautions]

- 1. Stanley LED Lamps have semiconductor characteristics and are designed to ensure high reliability. However, the performance may vary depending on usage conditions
- 2. Absolute Maximum Ratings are set to prevent LED lamps from failing due to excess stress(temperature, current, voltage, etc.). Usage conditions must not exceed the ratings for a moment, nor do reach one item of absolute maximum ratings simultaneously.
- 3. In order to ensure high reliability from LED Lamps, variable factors that arise in actual usage conditions should be taken into account for designing. (Derating of TYP., MAX Forward Voltage, etc.)
- 4. Please insert Protective Resistors into the circuit in order to stabilize LED operation and to prevent the device from igniting due to excess current.
- 5. Please check the actual performance in the assembly because the Specification Sheets are described for LED device only.
- 6. Please refrain from looking directly at the light source of LED at high output, as it may harm your vision.
- 7. The products are designed to operate without failure in recommended usage conditions. However, please take the necessary precautions to prevent fire, injury, and other damages should any malfunction or failure arise.
- 8. The products are manufactured to be used for ordinary electronic equipment. Please contact our sales staff beforehand when exceptional quality and reliability are required, and the failure or malfunction of the products might directly jeopardize life or health (such as for airplanes, aerospace, transport equipment, medical applications, nuclear reactor control systems and so on).
- 9. When there is a process of supersonic wave welding etc. after mounting the product, there is a possibility of affecting on the reliability of junction part in package (junction part of die bonding and wire bonding). Please make sure there is no problem before using.
- 10. The formal specification sheets shall be valid only by exchange of documents signed by both parties.



TPS1195WB-1-TR

This product is baked (moisture removal) before packaging, and is shipped in moisture-proof packaging (as shown below) to minimize moisture absorption during transportation and storage. However, with regard to storing the products, Stanley recommends the use of dry-box under the following conditions is recommended. Moisture-proof bag as the packaging is made of anti-static material but packaging box is not.

[Recommended storage condition / Products warranty period]

| Temperature | +5 to 30°C |
|-------------|------------|
| Humidity | Under 60% |

In the case of the package unopened, **1 year under** [Recommended storage condition]. Please avoid rapid transition from low temp. condition to high temp. condition and storage in corroding and dusty environment.

[Time elapsed after package opening]

The package should not be opened until immediately prior to its use, and please keep the time frame between package opening and soldering which is [maximum 1 year].

If the device needs to be soldered twice, both soldering operations must be completed within the year.

If any components should remain unused, please reseal the package and store them under the conditions described in the [Recommended storage conditions] above.

This product must be required to perform baking process (moisture removal) for 48h (Min.) to 72h (Max.) at 60±5 degrees Celsius if following conditions apply.

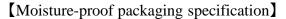
- 1. The enclose blue silica gel, which indicates the moisture level within the package, changes or loses its blue color.
- 2. If 1 year has passed after the package has been opened once.

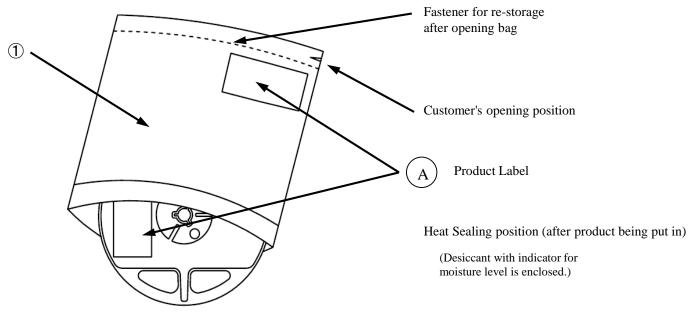
Baking process should be performed after LED having been taken out of the package.

Baking may be performed in the tape-reel form, however if it is performed with the reel stacked over one another, it may cause deformation of the reels and taping materials and later obstruct mounting. Please handle only once it has returned to room temperature. Provided that, baking process shall be 2 times Max.



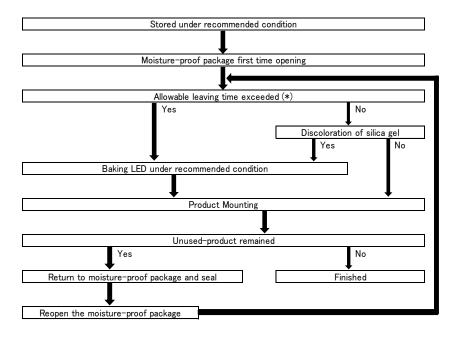
TPS1195WB-1-TR





| No. | Part name | Material | Remarks |
|-----|--|-----------|---------------------|
| 1) | Moisture-proof bag with aluminum layer | PET+Al+PE | with ESD protection |

[Flow chart-package opening to mounting]



Allowable leaving time means the maximum allowable leaving time after opening package, which depends on each LED type.

The allowable leaving time should be calculated form the first opening of package to the time when soldering process is finished.

When judging if the allowable leaving time has exceeded or not, please subtract the soldering time. The allowable leaving time after reopening should be calculated form the first opening of package, or from the time when baking process is finished.



TPS1195WB-1-TR

30 reels

[Packing box]

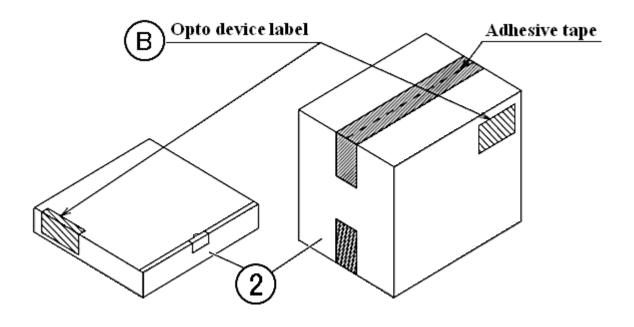
(RoHS2/ELV compliant)

| | | _ |
|----------|----------------------------------|---------------------|
| Box Type | Outline dimension L × W × H (mm) | Capacity of the box |
| Type A | 280 × 265 × 45 (mm) | 3 reels |
| Type B | 310 × 235 × 265 (mm) | 15 reels |

 $440 \times 310 \times 265 \text{ (mm)}$

The above measurements are reference values.

Type C



 $\label{eq:Type A} Type \ A$ $\mbox{Material / box : Cardboard C5BF}$

Type B,C

Material / box : Cardboard K5AF

Partition : Cardboard K5AF

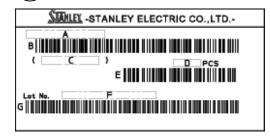
| NO. | PART NAME | MATERIAL | REMARKS |
|-----|-------------|------------|-------------|
| 2 | Packing Box | Corrugated | without ESD |
| | | Cardbord | protection |



TPS1195WB-1-TR

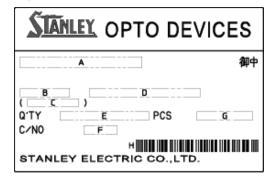
【 Label specification】 (acc.to JIS-X0503(Code-39)

(A) Product label



- A. Parts number
- B. Bar-code for parts number
- C. Parts code (In-house identification code for each parts number)
- D. Packed parts quantity
- E. Bar-Code for packed parts quantity
- F. Lot number & rank (refer to lot number notational system for details)
- G. Bar-code for lot number & rank

(B) Opto device label



- A. Customer name
- B. Parts type
- C. Parts code
- D. Parts number
- E. Packed parts quantity
- F. Carton number
- G. Shipping date
- H. Bar-code for in-house identification number

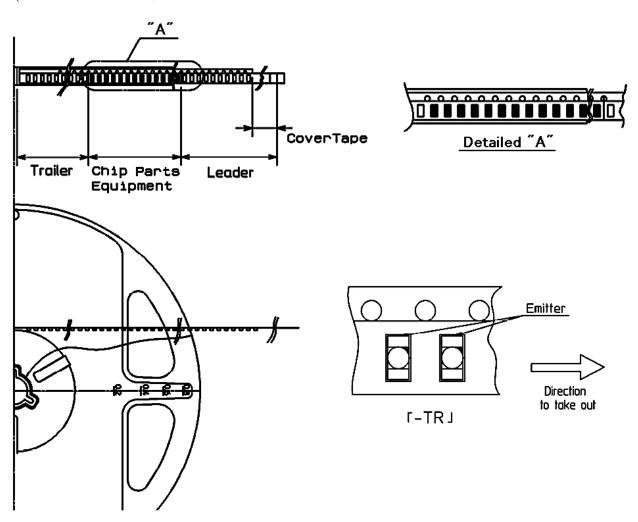
<Remarks> Bar-code font : acc.to Code-39 (JIS-X0503)



Taping and reel specifications

TPS1195WB-1-TR

(acc.to JIS-C0806-03)



Note

[&]quot;-TR" means cathode side of LEDs should be placed on the sprocket-hole side.

| Items Specifications | | Specifications | Remarks |
|--------------------------|------------|--|---|
| I and an area | Cover-tape | Cover-tape shall be longer than 300mm without carrier-tape | The end of cover-tape shall be held with adhesive tape. |
| Leader area Carrier-tape | | Empty pocket shall be more than 25 pieces. | Please refer to the above figure for Taping & reel orientation. |
| Trailer area | | Empty pocket shall be more than 40 pieces. | The end of taping shall be inserted into a slit of the hub. |



Taping and reel specifications

TPS1195WB-1-TR

(acc.to JIS-C0806-03)

2,000parts/reel

[Qty. per Reel]

[Mechanical strength]

Cover-tape adhesive strength shall be $0.1 \sim 1.0 N$ (An angle between carrier-tape and cover-tape shall be 170 deg.) Both tapes shall be so sealed that the contained parts will not come out from the tape when it is bent at a radius of 25mm.

[Others]

Reversed-orientation, Up-side down placing, side placing and out of spec. parts mix shall not be held.



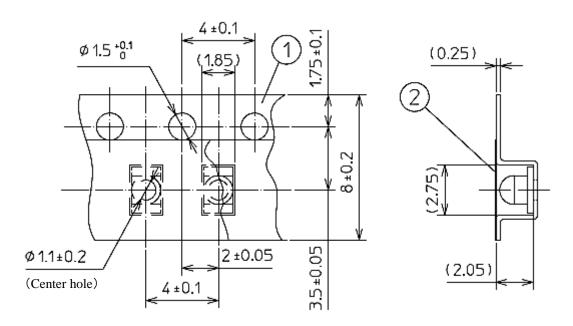
Taping and reel specifications

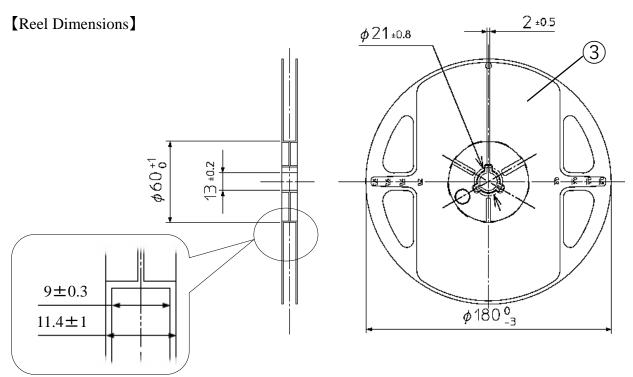
TPS1195WB-1-TR

Unit: mm

(acc.to JIS-C0806-03)

【Taping Dimensions】



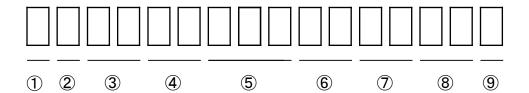


| NO. | PART NAME | REMARKS |
|-----|--------------|-------------------|
| 1 | Carrier-tape | Conductive Grade |
| 2 | Cover-tape | Anti-Static Grade |
| 3 | Carrier-reel | Conductive Grade |



Lot number notational system

TPS1195WB-1-TR



- ① Idigit: Production location (mark identify alphabet)
- ② Idigit : Production year (The last digit of production year $2025 \rightarrow 5$, $2026 \rightarrow 6$, $2027 \rightarrow 7$, $2028 \rightarrow 8 \cdots$)
- ③ 2digits: Production month (Jan. to Sep., should be 01,02,03 ···)
- 4 2digits : Production date
- ⑤ 3digits: Serial number
- 6 2digits: Tape and reel following number
- 7 2digits : Total power rank.

(If total power rank is 1 digit, "-" shall be dashed on the place for the second digit.

If there is no identified rank, "--" is used to indicate.)

8 - 2digits: Wavelength rank

(If wavelength rank is 1 digit, "-" shall be dashed on the place for the second digit.

If there is no identified rank, "--" is used to indicate.)

9 - 1digit: VF Rank (If rank is not defined, "-" is described.)



Compliance with RoHS2/ELV

TPS1195WB-1-TR

This product is in compliance with RoHS2/ELV.

Prohibition substance and it's criteria value of RoHS2/ELV are as follows.

- RoHS2 instruction ... Refer to following 1 to 10.
- •ELV instruction ... Refer to following 1 to 4.

| No. | Substances | Threshold |
|-----|---------------------------------------|-----------------|
| 1 | Lead and its compounds | 0.1% (1,000ppm) |
| 2 | Mercury and its compounds | 0.1% (1,000ppm) |
| 3 | Cadmium and its compounds | 0.01% (100ppm) |
| 4 | Hexavalent chromium compounds | 0.1% (1,000ppm) |
| 5 | PBB : Polybrominated Biphenyls | 0.1% (1,000ppm) |
| 6 | PBDE : Polybrominated Biphenyl Ethers | 0.1% (1,000ppm) |
| 7 | DEHP : Bis (2-ethylhexyl) phthalate | 0.1% (1,000ppm) |
| 8 | BBP: Butyl benzyl phthalate | 0.1% (1,000ppm) |
| 9 | DBP : Dibutyl phthalate | 0.1% (1,000ppm) |
| 10 | DIBP: Diisobutyl phthalate | 0.1% (1,000ppm) |



Reliability testing result

TPS1195WB-1-TR

1. Reliability testing result

| Test item | Test condition | |
|--------------------------------------|---|--|
| Endurance operational test | Ta=25°C, 1,000h , Pc=75mW | |
| Humidity-resistance operational test | Ta=60°C, RH=90%, 1,000h, V _{CE} =5V | |
| High temperature operational test | Ta=85°C, 1,000h, V _{CE} =5V | |
| Low temperature operational test | Ta=-40°C, 1,000h, V _{CE} =5V | |
| Heat cycle test | Storage temp. min, value (30min.) to storage temp. max,value (30min.) 5cycles | |
| High temperature shelf test | Ta=Storage temp. max., value t=1,000h | |
| Low temperature shelf test | Ta=Storage temp. min., value t=1,000h | |
| Reflow resistance test | Moisture soak: Ta=30°C, RH=70%, 72h Preheating: 150 to 180°C 120sec. max. Soldering: 230 to 260°C 40sec. max. | |

2. Failure criteria

| Item | Symbol | Test Condition | Failure Criteria |
|---------------------|--------|---------------------------------|--|
| Dark Current | I_D | $V_{CE} = 5V$ | $I_D < 0.1 \mu A$ |
| Photo Current | Ic | $V_{CE} = 5V$, $Ee = 5mw/cm^2$ | Initial value \times 0.7 < Ic < Initial value \times 1.3 |
| Cosmetic Appearance | - | - | Notable, discoloration, deformation and cracking |



TPS1195WB-1-TR

Special Notice to Customers Using the Products and Technical Information Shown in This Data Sheet

- The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.
- 2) For the purpose of product improvement, the specifications, characteristics and technical data described in the data sheets are subject to change without prior notice. Therefore it is recommended that the most updated specifications be used in your design.
- 3) When using the products described in the data sheets, please adhere to the maximum ratings for operating voltage, heat dissipation characteristics, and other precautions for use. We are not responsible for any damage which may occur if these specifications are exceeded.
- 4) The products that have been described to this catalog are manufactured so that they will be used for the electrical instrument of the benchmark (OA equipment, telecommunications equipment, AV machine, home appliance and measuring instrument).
 - The application of aircrafts, space borne application, transportation equipment, medical equipment and nuclear power control equipment, etc. needs a high reliability and safety, and the breakdown and the wrong operation might influence the life or the human body. Please consult us beforehand if you plan to use our product for the usages of aircrafts, space borne application, transportation equipment, medical equipment and nuclear power control equipment, etc. except OA equipment, telecommunications equipment, AV machine, home appliance and measuring instrument.
- 5) In order to export the products or technologies described in this data sheet which are under the "Foreign Exchange and Foreign Trade Control Law," it is necessary to first obtain an export permit from the Japanese government.
- 6) No part of this data sheet may be reprinted or reproduced without prior written permission from Stanley Electric Co., Ltd.
- 7) The most updated edition of this data sheet can be obtained from the address below: http://www.stanley-components.com/en/